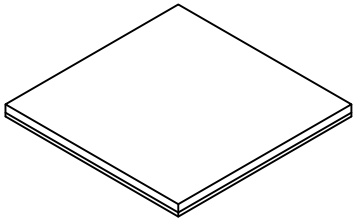
HMCCA,01/24/00,10:30:18,PB0NL2D101,M-01 GREME,08/12/01,09:16:15,DCLZ7Q

REVISION HISTORY							
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	DATABASE FILE NAME	GERBER FILE NAME	INCORPORATOR	DATE
00	C9763	INITIAL RELEASE	LMACK	N/A	N/A	LMACK	12/27/00
01	A50143	ROW OF BALLS ARE MISSING ON THE BOTTOM SIDE	SWOON	N/A	N/A	SWOON	12/27/00
02	C11534	ADDED 316 FOOTPRINT	GREME	N/A	N/A	SDEFO	02/28/01
03	C13383	ADDED 300 FOOTPRINT	GREME	N/A	N/A	ACOPI	08/20/01



7. REFERENCE SPECIFICATIONS:
   A. AWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 400.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 20 X 20.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.80mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

DECIMAL
X.X ±0.1
X.XX ±0.05
X.XXX ±0.030

ANGULAR ±1°

INTERPRET DIM AND TOL PER ASME Y14.5M - 1994

MATERIAL: N/A

FINISH: N/A

DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS	DATE
DESIGNED: LMACK	08/14/00
CHECKED: DARNO	08/14/00
PRODUCT MANAGER: TPANC	08/14/00
RELEASED: RHOLM	08/23/00

Amkor Technology, Inc.
Chandler, Arizona, USA
Anam Semiconductor, Inc.,
Seoul, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor Technology / ANAM Semiconductor

TITLE: PACKAGE OUTLINE - MAF, 20 X 20 MATRIX, 17.00mm X 17.00mm X 1.40mm, 0.70mm MOLD CAP, 0.46mm BALL, 0.80mm PITCH, LAMINATE SUBSTRATE, AWW

SIZE	SID NUMBER	DWG NUMBER	REV
A3	N/A	81095	03

STRIP DWG NUMBER/REV	PKG OUTLINE DWG NO.	SCALE	SHEET
N/A	N/A	NONE	1 OF 4

FORM NO: MBFLAM1C1.DWG